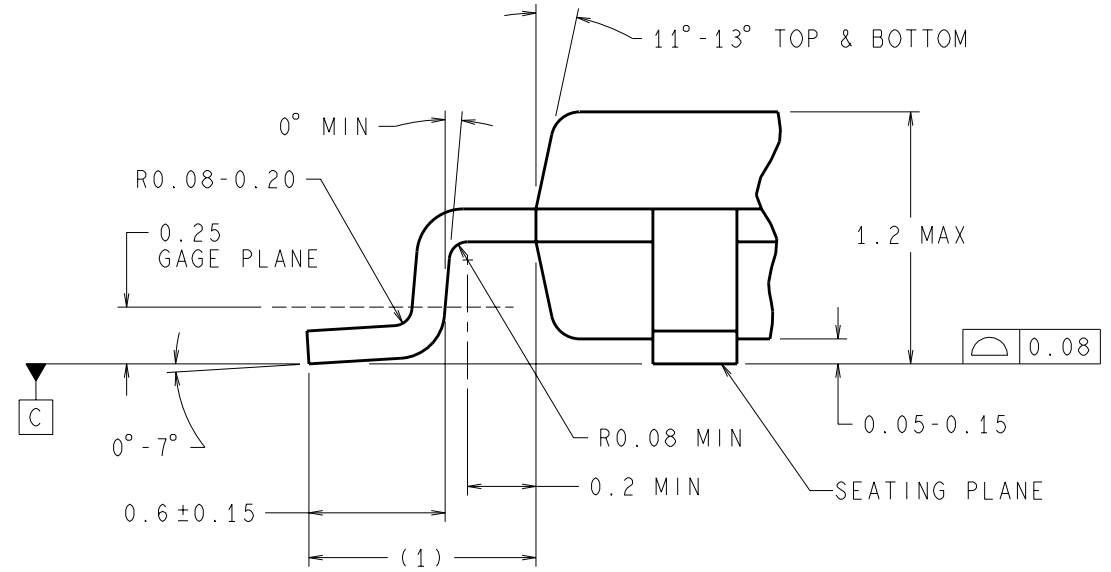
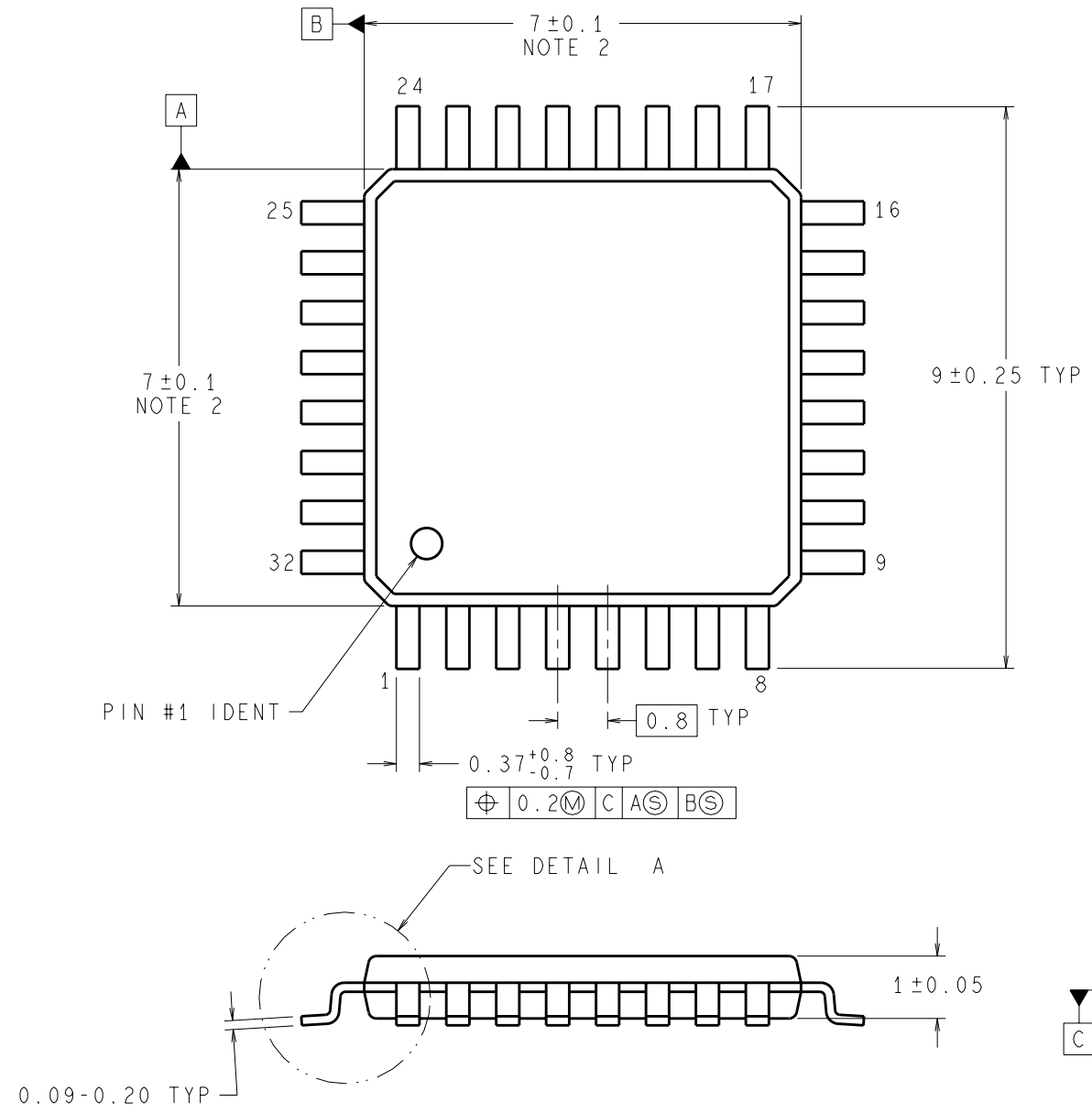


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10989	06/06/1995	TL/HJK
B	TITLE: TQFP WAS PQFP; UPDATE NOTE 3 ADD GEOMETRIC TOLERANCE	12317	12/03/1999	ACS/MS/RW



DETAIL A  
TYP, SCALE: 50X

DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
  - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
  - REFERENCE JEDEC REGISTRATION MS-026, VARIATION ABA,  
DATED FEB 1999.

APPROVALS	DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090 <b>TQFP, JEDEC METRIC, 7 X 7 X 1.0mm, 32 LEAD</b>		
DRAWN <b>T. LEQUANG</b>	03/21/1995			
DFTG. CHK. <b>THANH LEQUANG</b>	12/03/1999			
ENGR. CHK. <b>RANDALL WALBERG</b>	12/03/1999			
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	(SC)MKT-VBA32A	B
FORMERLY:			SHEET 1 of 1	